

/ Descriptions

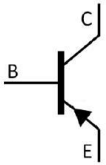
JF K) * \$* GE G

/ Features

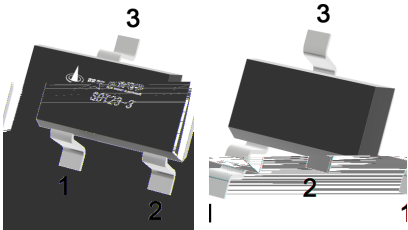
9I)J; (. /)D : H

/ Applications

/ Equivalent Circuit



/ Pinning



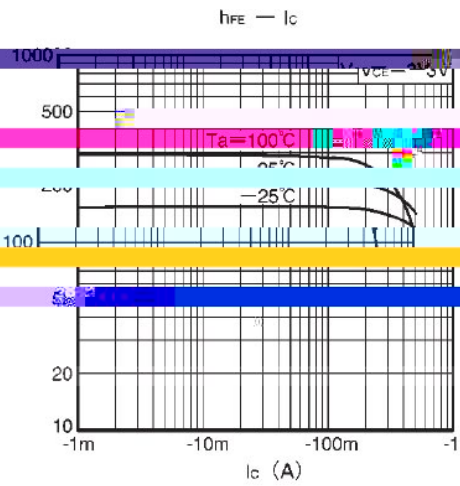
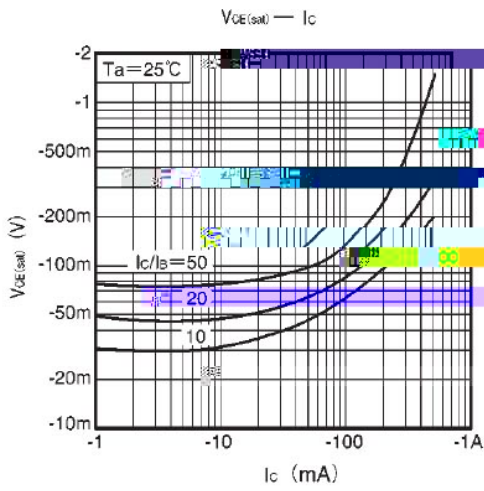
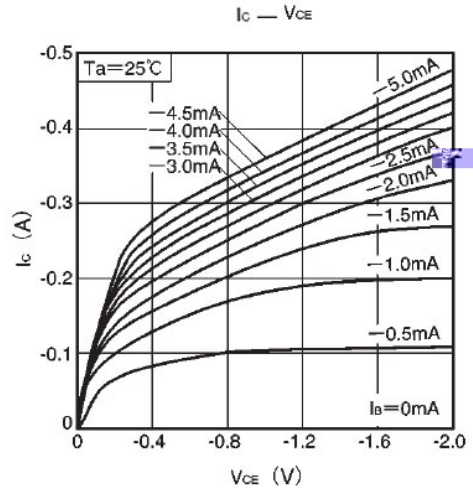
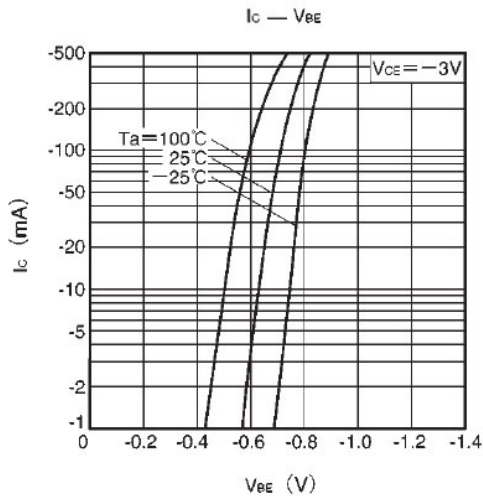
/ hFE Classifications & Marking

/ Absolute Maximum Ratings(Ta=25)

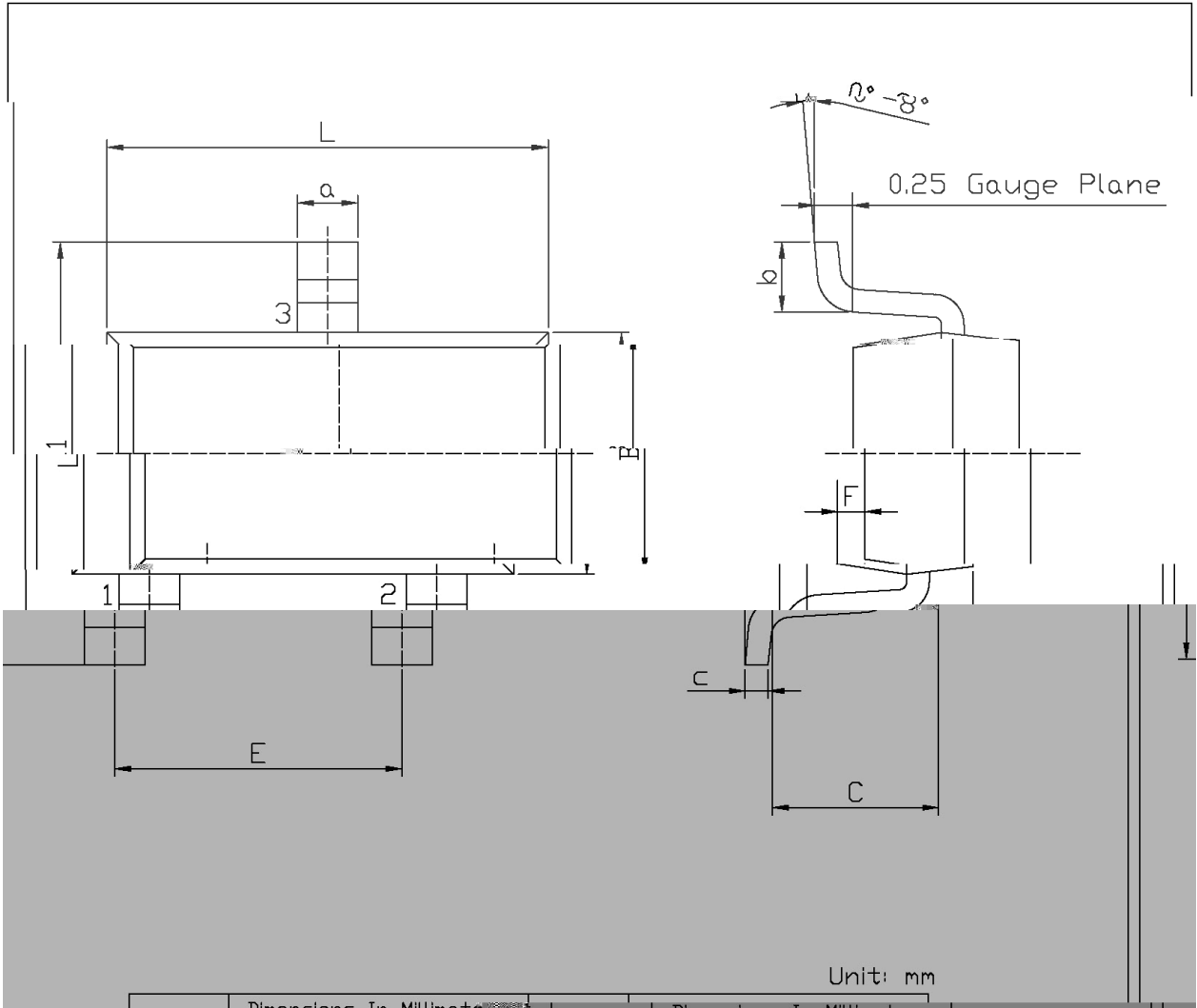
/ Electrical Characteristics(Ta=25)

		μ				
		μ				
						μ
						μ
						μ

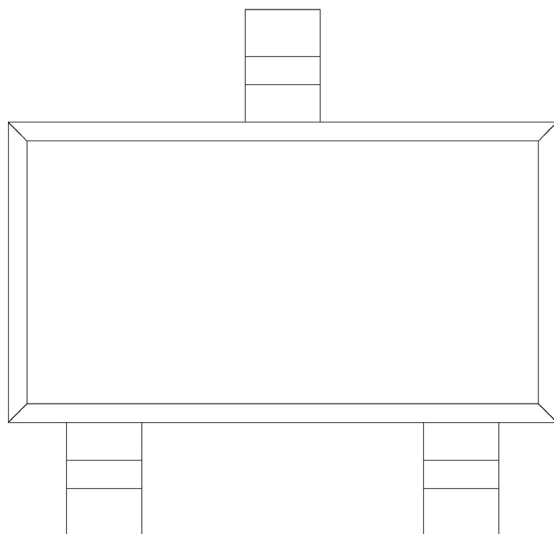
/ Electrical Characteristic Curve



/ Package Dimensions

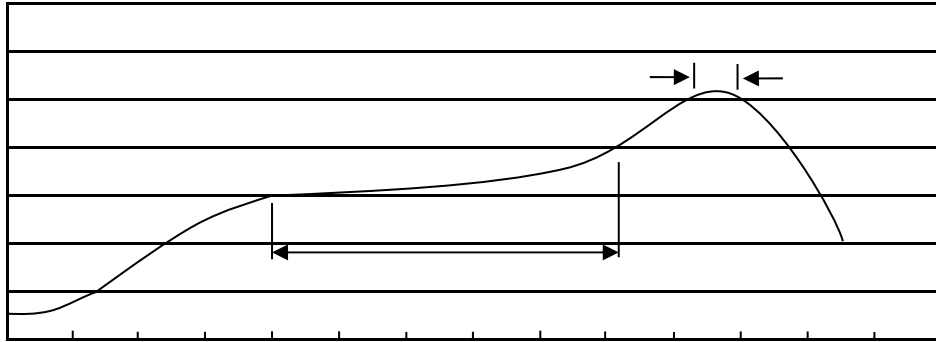


/ Marking Instructions



H
8K
I

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ± ± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱

/ Notices